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Ultra Communications Awarded SBIR Phase II and BAA Awards to Develop Optical Coupling to Waveguides or Fibers within Rigid Structures

Vista, California, September 20, 2010 - Ultra Communications, Inc today announced that it has been two awards related to the development of technology for integrating optical signals within rigid structures. This technology leverages alignment tolerant optical coupling methods and is applicable to chip-to-chip, backplane and box-level interconnections.

AFRL SBIR Phase II – Alignment Tolerant Components for Robust Optical Signal Distribution.

This is an opportunity to create robust optical interconnect technology compatible with the open standards for embedded systems in the aerospace market. The key concepts are the placement of sensitive optical waveguides within rigid structures and the elimination of physical-contact fiber interfaces that are susceptible to self-contamination. We focus on optical interconnect for 100's of fiber 'within the box' (including intra-board and board-to-board) and to the box connector interface.

AFRL BAA Phase 0 – Manufacturing of Optical Connector System for Harsh Environments.

This program investigates the manufacturing process for embedding components that couple light into waveguides within rigid board structures. We will rely on a combination of precision laser processing, mechanical features on the rigid-board and pick-and-place equipment, all available today. The process is similar to the cost-effective methods used to embed passive electrical components within PCB's today. By embedding optical paths within rigid structures, we enable implementation of higher channel count systems and save significant program dollars through increased reliability.

About Ultra Communications

Ultra Communications (UltraComm) supplies highly compact and robust photonic components for harsh environment applications, such as satellites, military airframes, UAV, missiles and cell phone base station applications. We have developed a hybrid IC and optoelectronic integration approach that features: Standard planar manufacturing of photonic packages, Single chip integration of multiple functions—transmitters, receivers and built-in-test, high speed digital (10 Gbps) or RF photonic components, ability to optically monitor Vertical Cavity Surface Emitter Lasers (VCSEL) on a per-channel basis, and operation over a wide temperature range and in radiation environments. Ultra Communications is headquartered in Vista, California (in the greater San Diego area). Additional information is available on the web at www.ultracomm-inc.com.

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